

## Thermally Stable Solder Paste No-Clean Sn63/Pb37 T4 (250g Jar)

### Product Highlights

**Revolutionary Formula: No Refrigeration Required!**

Printing speeds up to 125mm/sec  
Long stencil life  
Wide process window  
Clear residue

Low voiding  
Excellent wetting compatibility on most board finishes  
Print grade  
Compatible with enclosed print heads  
REACH Compliant

### Specifications

|                      |                                                                      |
|----------------------|----------------------------------------------------------------------|
| Alloy:               | Sn63/Pb37                                                            |
| Mesh Size:           | T4                                                                   |
| Micron (µm) Range:   | 20-38                                                                |
| Flux Type:           | Synthetic No-Clean                                                   |
| Flux Classification: | ROL0                                                                 |
| Metal Load:          | 90.25% Metal by Weight                                               |
| Melting Point:       | 183°C (361°F)                                                        |
| Packaging:           | 250g Jar                                                             |
| Shelf Life:          | Refrigerated >12 months, Unrefrigerated >12 months *See notes below: |

**\*Shelf Life Notes:** Chip Quik® solder paste is good past its quoted shelf life, regardless of refrigeration. Before use, visually inspect the solder paste to ensure it is not dried out or clumpy, or check stencil release. If stored in a jar, stir the product thoroughly for 2-3 minutes before inspection and use.

Chip Quik® solder paste is manufactured using Made in USA high quality synthetic flux and precision atomized metal powder. Chip Quik® solder paste is guaranteed for 12 months from date of manufacture, regardless of refrigeration. If you have any issues with our solder paste, please contact Chip Quik® directly for no charge warranty replacement. Please retain original bill of sale, and solder paste in original container as we may request its return for internal R&D testing purposes.

### Printer Operation

Print Speed: 25-125mm/sec  
Squeegee Pressure: 70-250g/cm of blade  
Under Stencil Wipe: Once every 10-25 prints, or as necessary

### Stencil Life

>12 hours @ 20-50% RH 22-28°C (72-82°F)  
>4 hours @ 50-70% RH 22-28°C (72-82°F)

### Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

### Storage and Handling

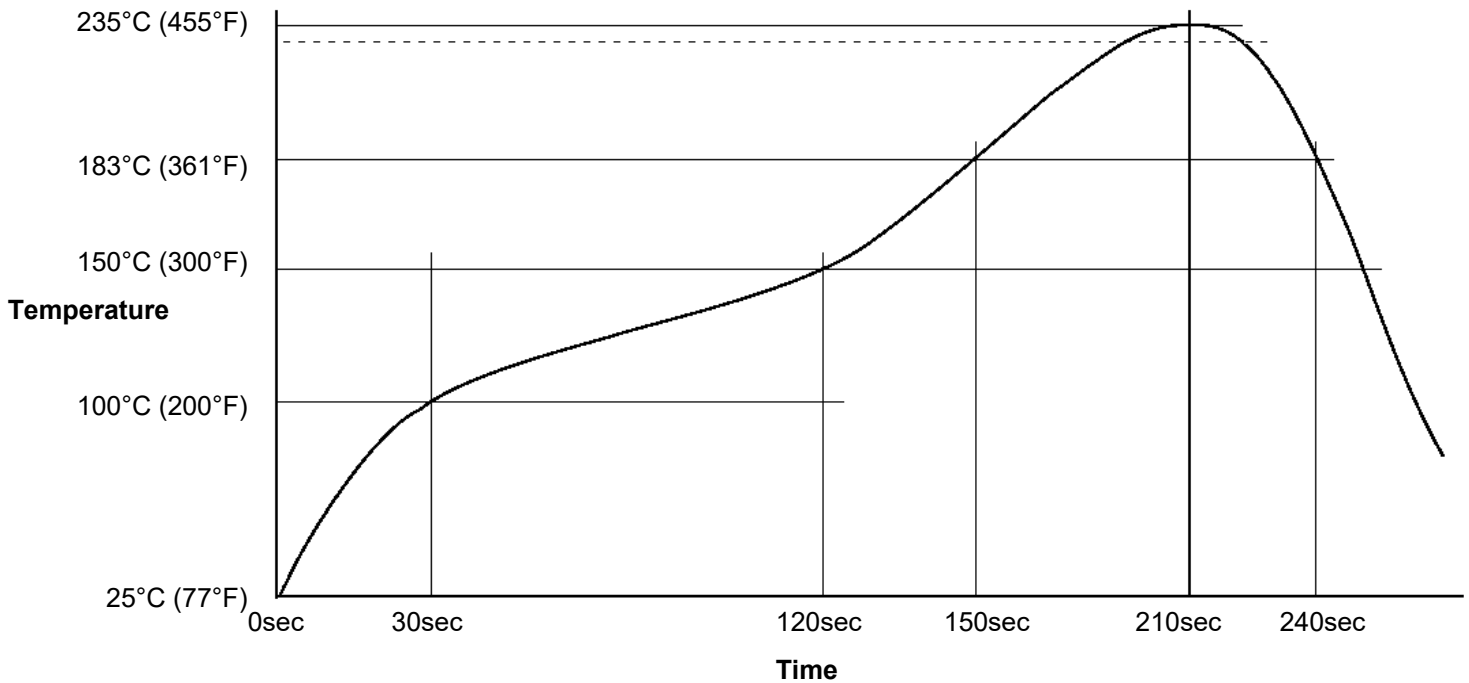
Store at room temperature 20-25°C (68-77°F). Do not freeze. Chip Quik Thermally Stable solder paste should be stored at its operating temperature (room temperature) of 20-25°C (68-77°F), therefore no warming time is required before use.

### Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

## Recommended Profile

Reflow profile for Sn63/Pb37 solder assembly, designed as a starting point for process optimization.



## Test Results

| Test J-STD-004 or other requirements as stated            | Test Requirement                                   | Result                                                     |
|-----------------------------------------------------------|----------------------------------------------------|------------------------------------------------------------|
| Copper Mirror                                             | IPC-TM-650: 2.3.32                                 | L: No breakthrough                                         |
| Corrosion                                                 | IPC-TM-650: 2.6.15                                 | L: No corrosion                                            |
| Quantitative Halides                                      | IPC-TM-650: 2.3.28.1                               | L: <0.5%                                                   |
| Electrochemical Migration                                 | IPC-TM-650: 2.6.14.1                               | L: <1 decade drop (No-clean)                               |
| Surface Insulation Resistance 85°C, 85% RH @ 168 Hours    | IPC-TM-650: 2.6.3.7                                | L: ≥100MΩ (No-clean)                                       |
| Tack Value                                                | IPC-TM-650: 2.4.44                                 | 33g                                                        |
| Viscosity – Malcom @ 10 RPM/25°C (x10 <sup>3</sup> mPa/s) | IPC-TM-650: 2.4.34.4                               | Print: 140-195, Dispense: 115-160                          |
| Visual                                                    | IPC-TM-650: 3.4.2.5                                | Clear and free from precipitation                          |
| Conflict Minerals Compliance                              | Electronic Industry Citizenship Coalition (EICC)   | Compliant                                                  |
| REACH Compliance                                          | Articles 33 and 67 of Regulation (EC) No 1907/2006 | Contains Lead (Pb) CAS# 7439-92-1<br>No other SVHC present |

## Conforms to the following Industry Standards:

|                                                                             |     |
|-----------------------------------------------------------------------------|-----|
| J-STD-004B, Amendment 1 (Solder Fluxes):                                    | Yes |
| J-STD-005A (Solder Pastes):                                                 | Yes |
| J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): | Yes |
| RoHS 2 Directive 2011/65/EU:                                                | No  |